

	TECI	HNICAL DATA SH	IEET	2 / 4
STRAIG	GHT JACK RECEI		R110.427.810	
	REEL OF		Series : MMCX	
PACKAGING			SPECIFICATION	
Standard 500	Unit 'W' option	Other Contact us		
ELECTRICAL CHARACTERISTICS			ENVIRONMENTAL	
VSWR 1.15 + 0,0500 Insertion loss TBD RF leakage - (Voltage rating 170 Dielectric withstanding voltage 250		GHz	Operating temperature -55/+155 ° C Hermetic seal NA Atm.cm3/s Panel leakage NA	
			OTHERS CHARACTERISTICS	
			Assembly instruc	ction
			Others :	
	ICAL CHARACTE	RISTICS		
Center contact retenti Axial force – Matin Axial force – Oppos Torque	ng end 7 osite end 7	/ N mini / N mini . N.cm mini		
Recommended torque Mating Panel nut	NA	N.cm N.cm		
Mating life Weight	100 0,2260	Cycles mini g		
Issue : 0650 B In the effort to improve necessary.	e our products, we reserve	e the right to make cha	anges judged to be	

TECHNICAL DATA SHEET

STRAIGHT JACK RECEPTACLE SMT TYPE

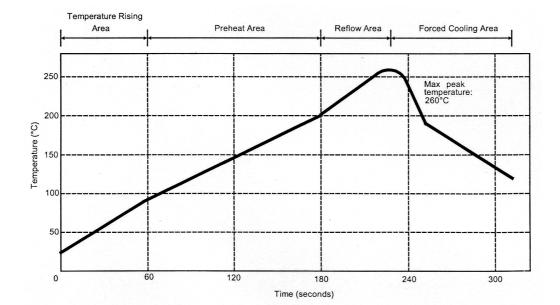
REEL OF 500

R110.427.810

Series : MMCX

SOLDER PROCEDURE

- Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 microms mini. (.006 inch mini). Verify that the edges of the zone are clean.
- Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. Aspiration port (see page 4) centered into body and push against it. A video camera is recommended for positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. Soldering by infra-red reflow. Below please find ,the typical profile to use.
- 4. Cleaning of printed circuit boards.
- 5. Verification of solder joints and position of the component by visual inspection.



TEMPERATURE PROFILE

ParAmeter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec



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